AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-8 (canceled).

Claim 9 (currently amended): ~~The surface acoustic wave filter according to Claim 6, wherein~~ A surface acoustic wave filter comprising:

a mount board including a land;

a device chip in which a wiring pattern including an IDT and a pad electrically connected to the IDT is provided on one of a pair of parallel and opposing principal surfaces of a piezoelectric substrate, the pad being disposed so as to oppose the land of the mount board, the pad and the land being electrically connected through a bump; and

a resin film covering the other principal surface of the piezoelectric substrate and sealing the device chip; wherein

an area of the one of the principal surfaces of the piezoelectric substrate is greater than an area of the other principal surface of the piezoelectric substrate; and

each peripheral surface of the piezoelectric substrate extending between the pair of principal surfaces includes a curved portion extending along an outer edge of the other principal surface of the piezoelectric substrate.

Claim 10 (currently amended): The surface acoustic wave filter according to Claim ~~6~~ 9, wherein the piezoelectric substrate is made of one of $LiTaO_3$ and $LiNbO_3$.

Claim 11 (currently amended): The surface acoustic wave filter according to Claim ~~6~~ 9, wherein the land is made of Au.

Claim 12 (currently amended): The surface acoustic wave filter according to Claim ~~6~~ 9, wherein the bump is made of one of Au and solder.

Claim 13 (currently amended): ~~The surface acoustic wave filter according to Claim 7, wherein~~ A surface acoustic wave filter comprising:

a mount board including a land;

a device chip in which a wiring pattern including an IDT and a pad electrically connected to the IDT is provided on one of a pair of parallel and opposing principal surfaces of a piezoelectric substrate, the pad being disposed so as to oppose the land of the mount board, the pad and the land being electrically connected through a bump; and

a resin film covering the other principal surface of the piezoelectric substrate and sealing the device chip; wherein

an area of the one of the principal surfaces of the piezoelectric substrate is greater than an area of the other principal surface of the piezoelectric substrate;

each peripheral surface of the piezoelectric substrate extending between the pair of principal surfaces includes a parallel planar portion which is substantially parallel to the pair of principal surfaces of the piezoelectric substrate and a vertical planar portion which is substantially perpendicular to the pair of principal surfaces of the piezoelectric substrate, such that each of the peripheral surfaces of the piezoelectric substrate includes a stepped portion including at least one step; and

a thickness of the at least one step is substantially 50% ± 15% of a thickness of the piezoelectric substrate.

Claims 14-25 (canceled).

Claim 26 (new): The surface acoustic wave filter according to Claim 13, wherein the piezoelectric substrate is made of one of $LiTaO_3$ and $LiNbO_3$.

Claim 27 (new): The surface acoustic wave filter according to Claim 13, wherein the land is made of Au.

Claim 28 (new): The surface acoustic wave filter according to Claim 13, wherein the bump is made of one of Au and solder.